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PATENT

S.N. 10/729,892

AMENDMENTS TO THE CLAIMS

Please amend the claims as shown below:

1. (Currently Amended) A method of forming a semiconductor package comprising:

providing a leadframe having a main panel, a cavity section, and a plurality of leads extending from the main panel into the cavity section, the main panel no greater than a first distance from an outer edge of the cavity section and at least a first lead of the plurality of leads extending no greater than the first distance from the cavity section toward the main panel with a proximal end of the first lead attaching to the main panel at an intersection of the first lead and the main panel wherein the main panel is coterminous with the proximal end of the first lead and does not extend past the proximal end of the first lead toward the cavity section;

encapsulating the cavity section of the leadframe to form a package body;

mechanically removing a first portion of the main panel and leaving a second portion of the main panel to form a portion of the first lead extending greater than the first distance from the package body; and

excising a third portion of the main panel away from the first lead.

2. (Previously Presented) The method of claim 1 wherein providing the leadframe having the main panel, the cavity section, and the plurality of leads extending from the main panel into the cavity section, the main panel no greater than the first distance from an outer edge of the cavity section includes forming the first distance no greater than approximately fifty microns.

ONS000515
PATENT

S.N. 10/729,892

3. (Previously Presented) The method of claim 1 wherein excising the third portion of the main panel away from the first lead includes leaving a fourth portion of the main panel attached to an end of at least one lead of the plurality of leads.

4. (Original) The method of claim 3 further including plating exposed portions of the plurality of leads.

5. (Original) The method of claim 4 further including excising the end of the at least one lead of the plurality of leads from the main panel after plating exposed portions of the plurality of leads.

6. (Previously Presented) The method of claim 1 wherein mechanically removing the first portion of the main panel and leaving the second portion of the main panel includes trimming the main panel to form the portion of the plurality of leads.

7. (Previously Presented) The method of claim 1 wherein mechanically removing the first portion of the main panel and leaving the second portion of the main panel includes forming the portion of the first lead extending no greater than about fifty microns from the package body.

8. (Original) The method of claim 1 further including plating the plurality of leads and the main panel prior to the step of forming the first portion of the main panel into the portion of the first lead.

ONS000515
PATENT

S.N. 10/729,892

9. (Previously Presented) The method of claim 1 wherein mechanically removing the first portion of the main panel and leaving the second portion of the main panel includes selectively forming the second portion of the main panel into a number of leads that is less than all of the plurality of leads.

10. (Previously Presented) The method of claim 1 wherein mechanically removing the first portion of the main panel and leaving the second portion of the main panel includes forming the second portion of the main panel into a number of leads that is equal to all of the plurality of leads.

11. (Original) The method of claim 1 wherein providing the leadframe having the main panel, the cavity section, and the plurality of leads extending from the main panel into the cavity section, the main panel no greater than the first distance from the outer edge of the cavity section includes forming the leadframe devoid of a dam-bar between the main panel and the cavity section.

12. (Cancelled)

13. (Cancelled)

14. (Cancelled)

15. (Cancelled)

16. (Cancelled)

17. (Cancelled)

ONS000515
PATENT

S.N. 10/729,892

18. (Previously Presented) A semiconductor packaging method comprising:

providing a leadframe having a main panel, a cavity section, and a plurality of leads extending from the main panel into the cavity section, at least a first lead of the plurality of leads extending no greater than a first distance from the cavity section toward the main panel; and mechanically removing a first portion of the main panel and leaving a second portion of the main panel attached to the first lead to form a portion of the first lead extending greater than the first distance from the cavity section.

19. (New) A method of forming a semiconductor package comprising:

providing a leadframe having a main panel, a cavity section, and a plurality of leads extending from the main panel into the cavity section, the main panel no greater than a first distance from an outer edge of the cavity section and at least a first lead of the plurality of leads extending no greater than the first distance from the cavity section toward the main panel and intersecting with the main panel to form an intersection without the main panel extending closer to the cavity section than the intersection;

encapsulating the cavity section of the leadframe to form a package body without the main panel extending closer to the cavity section than the intersection;

mechanically removing a first portion of the main panel and leaving a second portion of the main panel to form a portion of the first lead extending greater than the first distance from the package body; and

excising a third portion of the main panel away from the first lead.